UM1B~UM10B
Rev.C Feb.-2015

蓝箭电子
BLUE ROCKET ELECTRONICS
DATA SHEET

描述 / Descriptions

0.8A 表面贴装玻璃钝化整流桥，薄型 UMB 封装。
0.8A Surface Mount Glass Passivated Bridge Rectifier,UMB thin package.

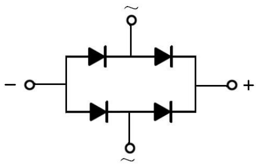
特征 / Features

玻璃钝化芯片，浪涌电流大，反向电压：100V~1000V，正向电流：0.8A，适用表面贴装。无卤产品。
Glass Passivated Chip Junction, High Surge Current Capability, Reverse Voltage :100 to 1000V, Forward Current: 0.8A, Designed for Surface Mount Application. Halogen free product.

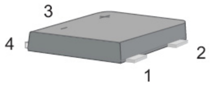
用途 / Applications

一般用途.
General purpose.

内部等效电路 / Equivalent Circuit



引脚排列 / Pinning



PIN	DESCRIPTION
1	Input Pin (~)
2	Input Pin (~)
3	Output Anode (+)
4	Output Cathode (-)

印章代码 / Marking

见印章说明。See Marking Instructions.

极限参数 / Absolute Maximum Ratings(Ta=25℃)

参数 Parameter	符号 Symbol	数值 Rating						单位 Unit
		UM1B	UM2B	UM4B	UM6B	UM8B	UM10B	
Maximum Repetitive Peak Reverse Voltage	V_{RRM}	100	200	400	600	800	1000	V
Maximum RMS voltage	V_{RMS}	70	140	280	420	560	700	V
Maximum DC Blocking Voltage	V_{DC}	100	200	400	600	800	1000	V
Average Rectified Output Current at Ta = 40℃	I_o	0.8						A
Peak Forward Surge Current 8.3 ms Single Half Sine Wave Superimposed on Rated Load (JEDEC Method)	I_{FSM}	25						A
Typical Junction Capacitance $^{\text{（Note1）}}$	C_i	13						pF
Typical Thermal Resistance $^{\text{（Note2）}}$	$R_{\theta JA}$	180						℃/W
Operating and Storage Temperature Range	T_j,T_{stg}	-55~150						℃

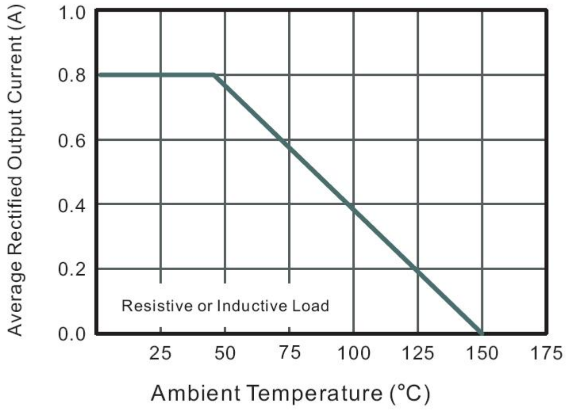
Note:

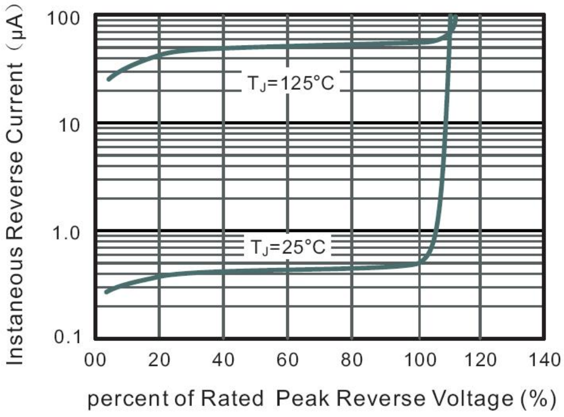
1. Measured at 1MHz and applied reverse voltage of 4 V D.C.
2. P.C.B. mounted with 4x0.1x0.1"(4x2.54x2.54mm) copper pad areas.

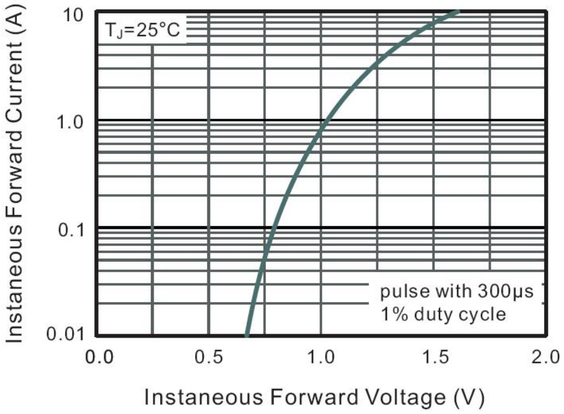
电性能参数 / Electrical Characteristics(Ta=25℃)

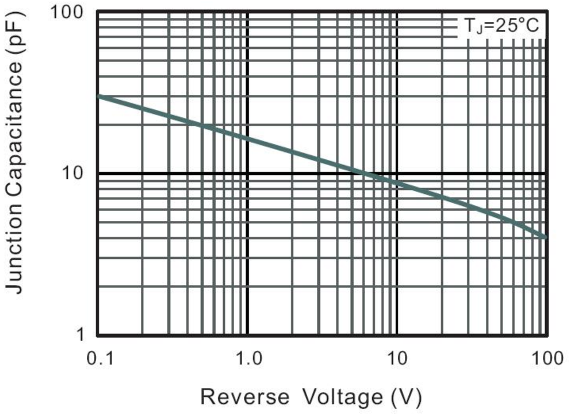
参数 Parameter	符号 Symbol	测试条件 Test Conditions	数值 Rating	单位 Unit
Forward Voltage per element	V_F	I_F=0.4A	1.0	V
		I_F=0.8A	1.1	
Maximum DC Reverse Current at Maximum DC Blocking Voltage	I_R	T_a=25℃	5.0	μA
		T_a=125℃	100	

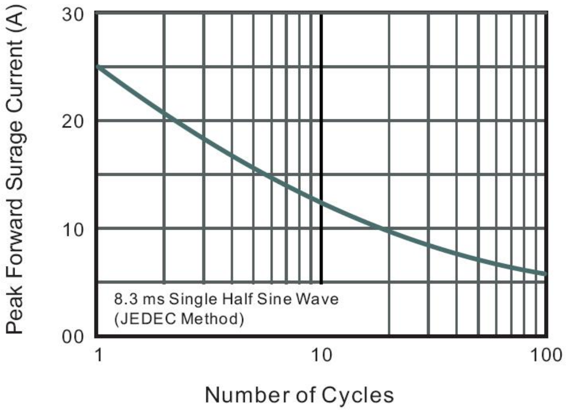
电参数曲线图 / Electrical Characteristic Curve





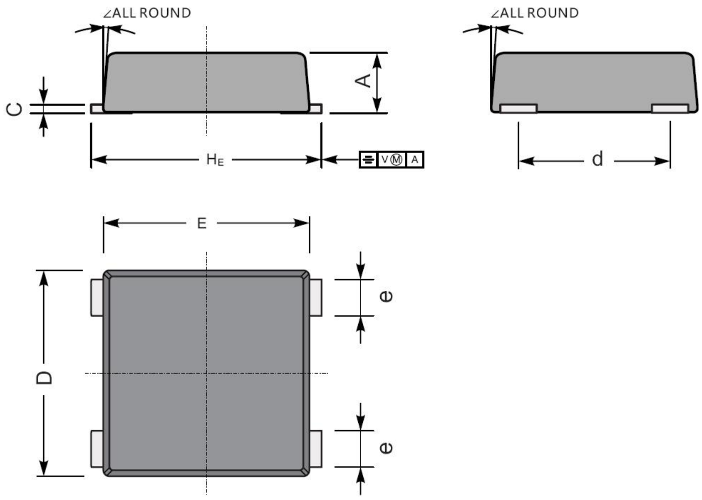






外形尺寸图 / Package Dimensions

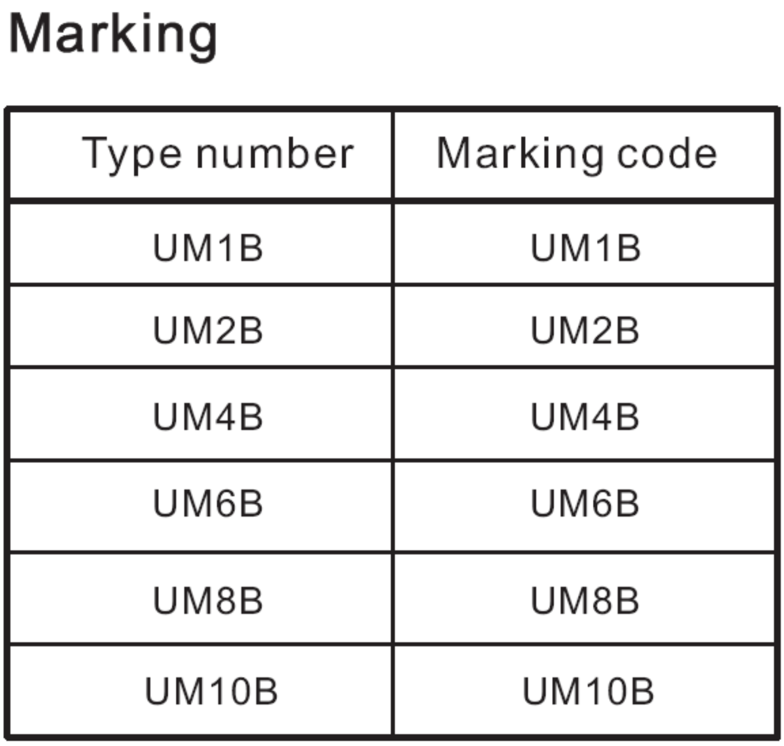
UMB



UMB mechanical data

UNIT		A	C	D	E	H_E	d	e	∠
mm	max	1.2	0.19	3.7	4.0	5.0	2.7	0.7	7°
	min	1.0	0.12	3.4	3.6	4.6	2.3	0.5	
mil	max	47	7.5	146	158	197	106	28	
	min	40	4.7	134	142	181	91	20	

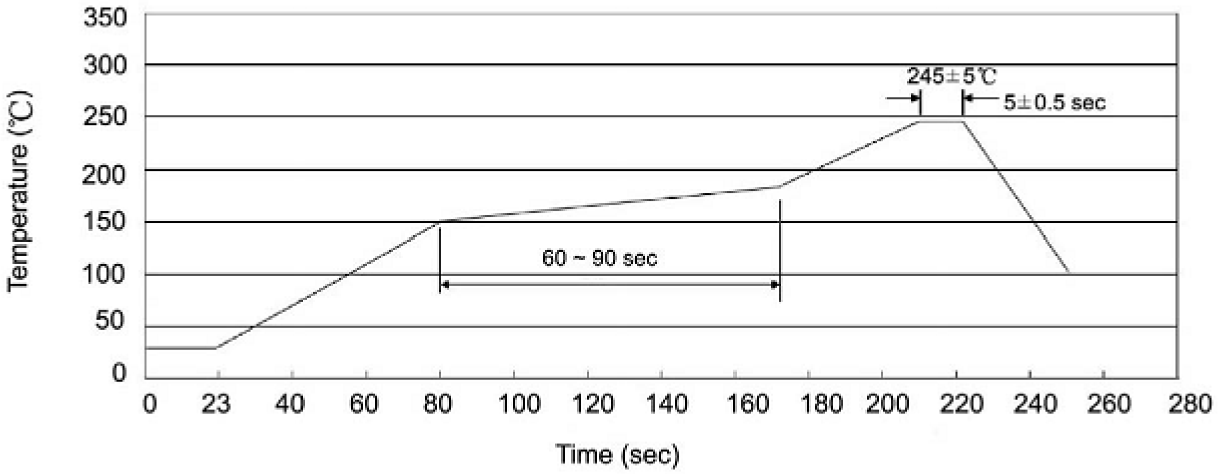
印章说明 / Marking Instructions



Marking

Type number	Marking code
UM1B	UM1B
UM2B	UM2B
UM4B	UM4B
UM6B	UM6B
UM8B	UM8B
UM10B	UM10B

回流焊温度曲线图(无铅) / Temperature Profile for IR Reflow Soldering(Pb-Free)



说明：	Note:
1、预热温度 25 ~ 150℃，时间 60 ~ 90sec;	1.Preheating:25~150℃, Time:60~90sec.
2、峰值温度 245±5℃，时间持续为 5±0.5sec;	2.Peak Temp.:245±5℃, Duration:5±0.5sec.
3、焊接制程冷却速度为 2 ~ 10℃/sec.	3. Cooling Speed: 2~10℃/sec.

耐焊接热试验条件 / Resistance to Soldering Heat Test Conditions

温度：260±5℃　　时间：10±1 sec.　　Temp.:260±5℃　　Time:10±1 sec

包装规格 / Packaging SPEC.

卷盘包装 / REEL

Package Type 封装形式	Units 包装数量					Dimension 包装尺寸 (unit: mm^3)		
	Units/Reel 只/卷盘	Reels/Inner Box 卷盘/盒	Units/Inner Box 只/盒	Inner Boxes/Outer Box 盒/箱	Units/Outer Box 只/箱	Reel	Inner Box 盒	Outer Box 箱

使用说明 / Notices